

**General Description:**

Schottky Barrier Diodes make use of the rectification effect of a metal to silicon barrier. They are ideally suited for high frequency rectification in switching regulators & converters. This device offers a low forward voltage performance in a power surface mount package in applications where size and weight are critical.

**Features:**

- Compact surface mount package with J-bend leads (SMC).
- 3.0 Watt Power Dissipation package.
- 3.0 Ampere, forward voltage less than 525 mV

**Ordering:**

- 13 inch reel (330 mm); 16 mm Tape; 3,000 units per reel.

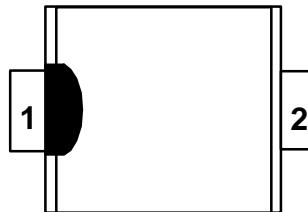
**Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

| Parameter  | Value       | Units |
|--|-------------|-------|
| Storage Temperature  | -65 to +150 | °C    |
| Maximum Junction Temperature   | -65 to +125 | °C    |
| Repetitive Peak Reverse Voltage (V <sub>RRM</sub> )                      | 40          | V     |
| Average Rectified Forward Current (T <sub>L</sub> = 100°C)               | 3.0         | A     |
| (T <sub>L</sub> = 90°C)  | 4.0         | A     |
| Surge Non Repetitive Forward Current<br>(Half wave, single phase, 60 Hz) | 80          | A     |
| Junction to Case for Thermal Resistance (R <sub>θJL</sub> )              | 11          | °C/W  |

\*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

SMC Package  
(DO-214AB)

Top Mark: B34

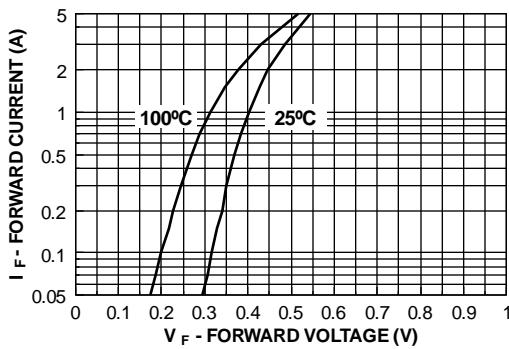
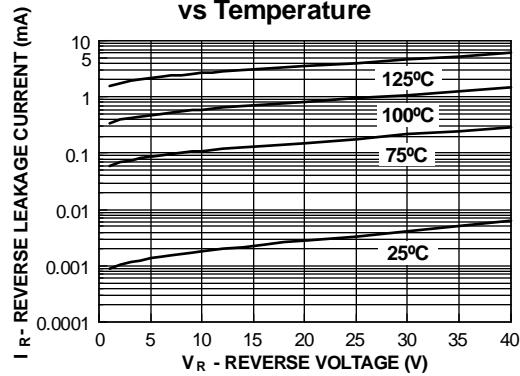
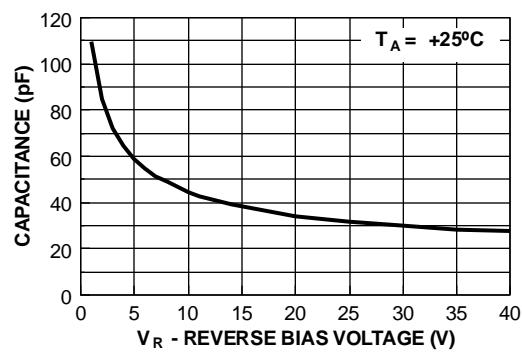


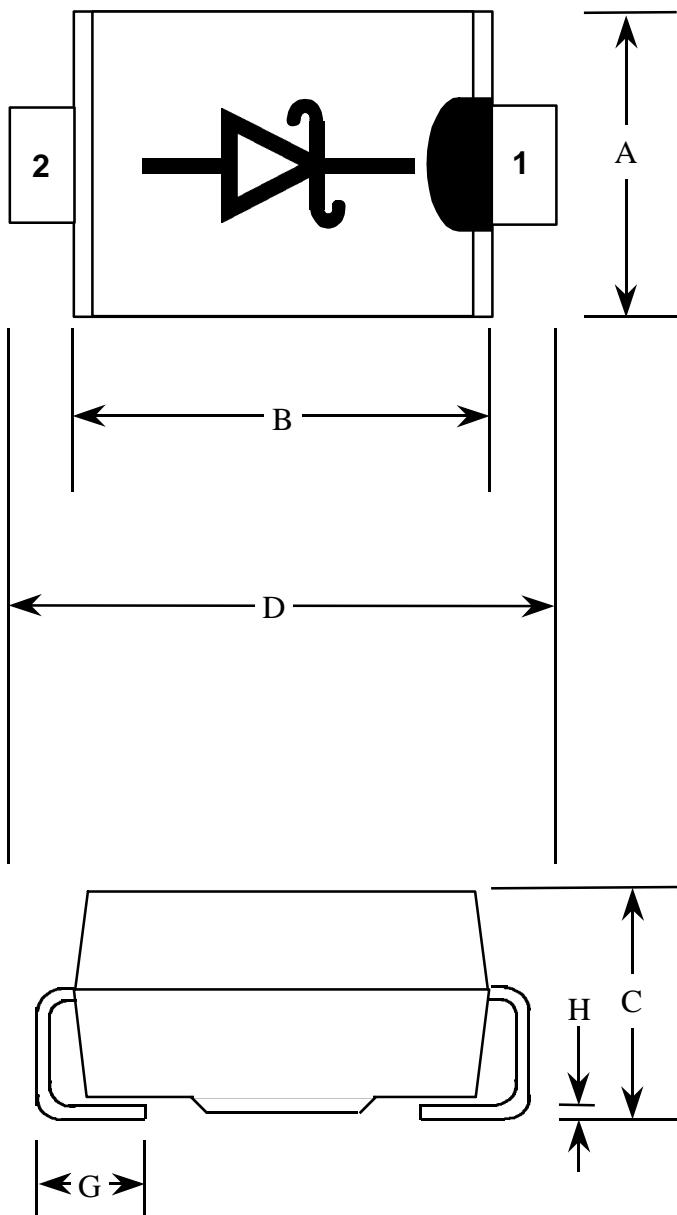
Actual Size

**Electrical Characteristics**

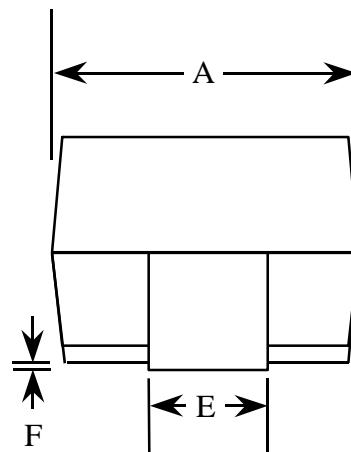
TA = 25°C unless otherwise noted

| SYM            | CHARACTERISTICS                                      | MIN | MAX       | UNITS    | TEST CONDITIONS   |
|----------------|--|-----|-----------|----------|---|
| I <sub>R</sub> | Reverse Leakage Current<br>PW 300 us, ≤2% Duty Cycle |     | 2.0<br>20 | mA<br>mA | V <sub>R</sub> = 40 V; T <sub>j</sub> = 25°C<br>V <sub>R</sub> = 40 V; T <sub>j</sub> = 100°C |
| V <sub>F</sub> | Forward Voltage<br>PW 300 us, ≤2% Duty Cycle         |     | 525       | mV       | I <sub>F</sub> = 3.0 A; T <sub>j</sub> = 25°C   |

**Forward Voltage  
vs Temperature****Reverse Leakage Current  
vs Temperature****Capacitance vs.  
Reverse Bias Voltage**



| Actual Size<br><b>DIM</b> | MIN<br>(mils) | MAX<br>(mils) | MIN<br>(mm) | MAX<br>(mm) |
|---------------------------|---------------|---------------|-------------|-------------|
| A                         | 220           | 245           | 5.59        | 6.22        |
| B                         | 260           | 280           | 6.60        | 7.11        |
| C                         | 79            | 103           | 2.00        | 2.62        |
| D                         | 305           | 320           | 7.75        | 8.13        |
| E                         | 115           | 125           | 2.92        | 3.18        |
| F                         | 4             | 8             | 0.10        | 3.18        |
| G                         | 30            | 60            | 0.76        | 1.52        |
| H                         | 6             | 12            | 0.15        | 0.31        |



**SMC PACKAGE**  
PACKAGE CODE = (MC)  
Fairchild Semiconductor's Criteria